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Quarterly Reliability Monitoring Results

Quarters: Q1/2022 to Q4/2023 Based on structural similarity

Supplier		User Part Number				
Nexperia B.V. Name of Laboratory Assembly reliability labs Based on AEC-Q101 Test		BZX585-B24-Q Part Description				
		SMD package				
		Test Conditions	Duration	# Lots	# Quantity	# Rejects
			TEST			
	Pre- and Post-Stress	T 05.00				
# E1	Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below
		JESD22-A113	24 hours			
	PC	Bake Tamb = 125 °C Soak Tamb = 85 °C, RH = 85%	24 nours 168 hours			
# A1	Preconditioning	Reflow soldering	3 cycles	1514	64430	0
# 11	Treconditioning	MIL-STD-750-1	5 cycles	1514	04450	0
	HTRB	M1038 Method A				
		$T_j = T_jmax$, VR = 80 % of rated reverse				
# B1	Bias	voltage	1000 hours	250	11400	0
		MIL-STD-750-1				
		M1038 Method B				
	SSOP	Tj = Tjmax, Iz = 100% of max. datasheet				
# B1b	Steady State Operational	reverse current	1000 hours	44	1920	0
	тс	JESD22-A104				
# A4	Temperature Cycling	-65 °C to Tjmax, not to exceed 150°C	1000 cycles	311	14080	0
" • • •	UHAST	JESD22-A118				
# A3 or	Unbiased HAST	Tamb = 130 °C, RH = 85 %	96 hours	311	14080	0
		JESD22-A102				
	AC	Tamb = 121 °C, RH = 100 %				
# A3 alt	Autoclave	Pressure = 205 kPa (29.7 psia)				
	H3TRB	JESD22-A101				
	High Humidity High	Tamb = $85 ^{\circ}$ C, RH = 85% , VR = 80% of				
# A2 alt	Temperature Reverse Bias		1000 hours	311	14080	0
		MIL-STD-750 Method 1037	2000 1100/3	J11	1000	~
	IOL	ton = toff, devices powered to insure ΔT_i =				
# A5	Intermittent Operating Life	, , ,	1000 hours	312	14120	0
						-
	RSH	JESD22-A111				
# C8	Resistance to Solder Heat	260 °C ± 5 °C	10 s	269	8070	0
	SD					
# C10	Solderability	J-STD-002		19	6660	0

[1] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1)

Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

2,68E+09

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